

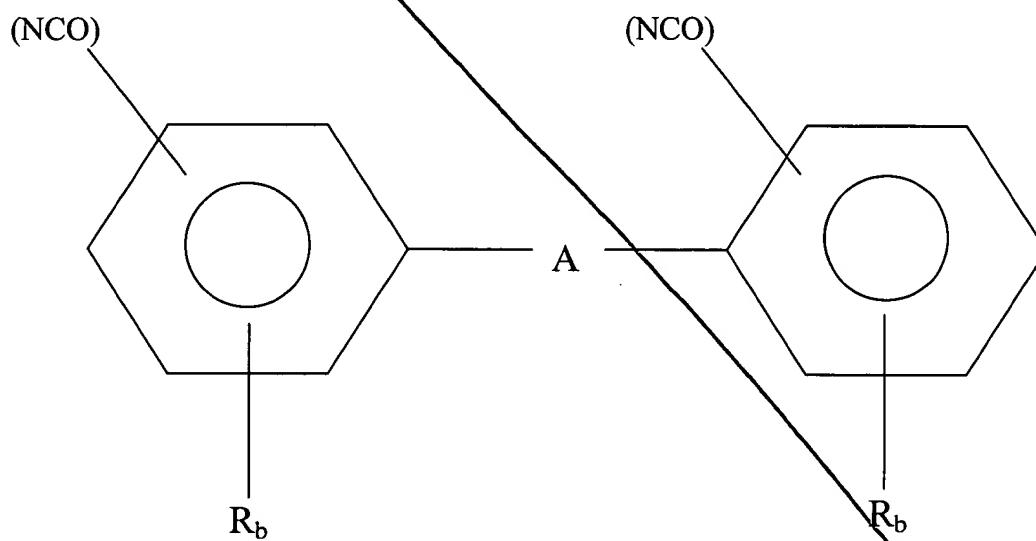
Sub 6.3

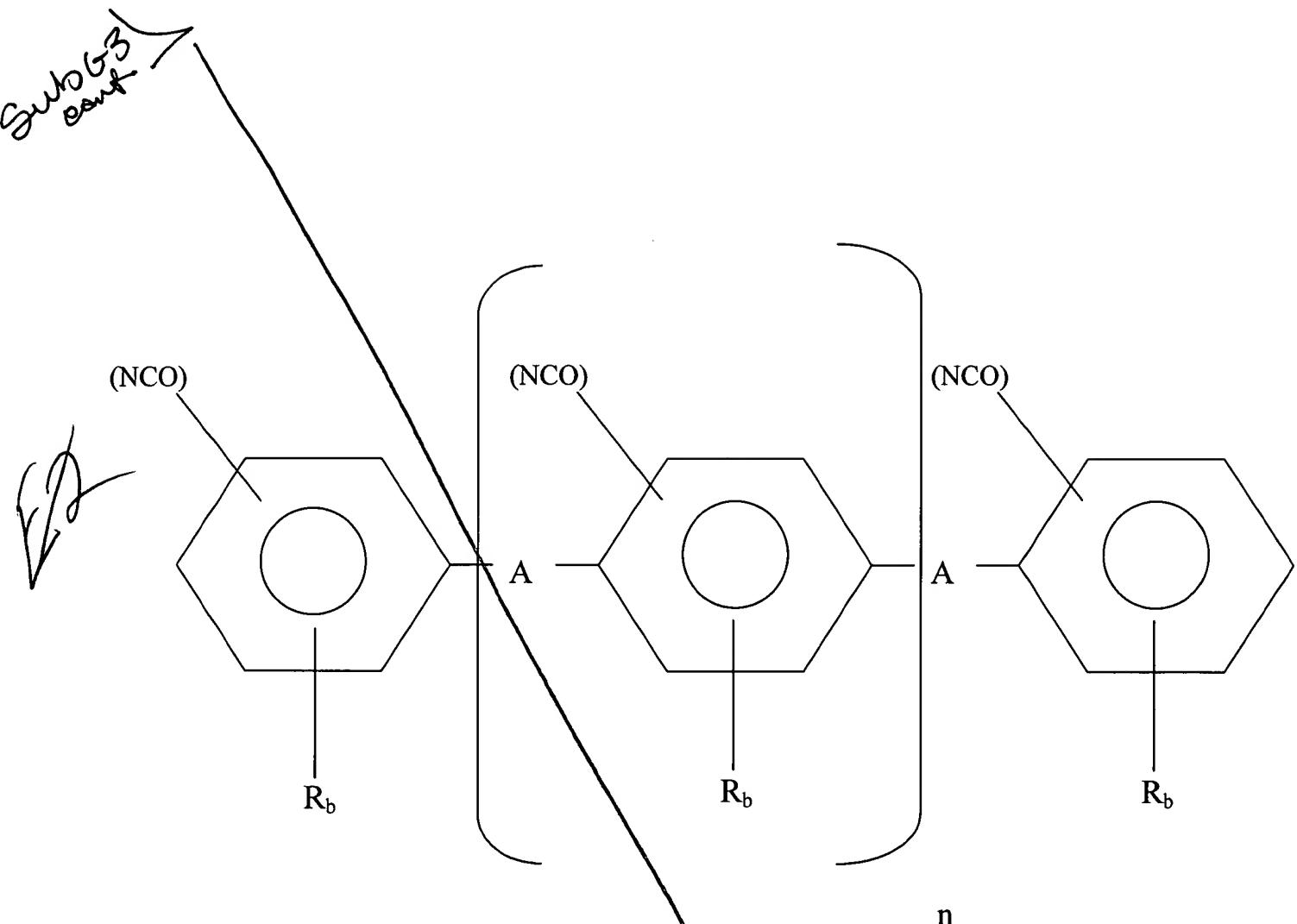
photocuring the composition to reinforce the solder joint, wherein photocuring the composition forms a resin in the composition from the precursor.

14. The method of claim 13, wherein the cyanate ester includes at least two cyanate groups and is curable through cyclotrimerization.

Sub 6.3 cont.

15. (TWICE AMENDED) The method of claim 13, wherein the cyanate ester is selected from the group consisting of compounds depicted by formulas 1 and 2:





wherein each a and b independently include integers from 0 to 3, and at least one a is not 0;
 wherein c includes integers from 0 to 1; wherein n includes integers from 0 to 8; wherein each
 each R is independently selected from the group consisting of non-interfering alkyl, aryl, alkaryl,
 heteroatomic, heterocyclic, carbonyloxy, carboxy, hydrogen, C₁₋₆ alkyl, C₁₋₆ allyl, C₁₋₆ alkoxy,
 halogen, maleimide, propargyl ether, glycidyl ether and combinations thereof; A is selected from
 the group consisting of C₁₋₁₂ polymethylene, CH₂, dicyclopentadienyl, ^{an allylene} aralkyl, aryl,

Subs 53

cycloaliphatic, $\text{CH}(\text{CH}_3)$, SO_2 , O, $\text{C}(\text{CF}_3)_2$, CH_2OCH_2 , CH_2SCH_2 , CH_2NHCH_2 , S, $\text{C}(\text{=O})$, $\text{OC}(\text{=O})$, OCOO , $\text{S}(\text{=O})$, $\text{OP}(\text{=O})$, $\text{OP}(\text{=O})(\text{=O})\text{O}$, alkylene radicals, $\text{C}(\text{CH}_3)_2$, and combinations thereof.

Subs 53

16. (AMENDED) The method of claim 13, wherein the cyanate ester is selected from the group consisting of cyanatobenzene, ^{or} 1,3- and 1,4-dicyanatobenzene, 2-tert-butyl-1,4-dicyanatobenzene, 2,4-dimethyl-1,3-dicyanatobenzene, 2,5-di-tert-butyl-1,4-dicyanatobenzene, tetramethyl-1,4-dicyanatobenzene, 4-chloro-1,3-dicyanatobenzene, 1,3,5-tricyanatobenzene, 2,2' 4,4'-dicyanatobiphenyl, 3,3',5,5'-tetramethyl-4,4'dicyanatobiphenyl, 1,3-dicyanatonaphthalene, 1,4-dicyanatonaphthalene, 1,5-dicyanatonaphthalene, 1,6-dicyanatonaphthalene, 1,8-dicyanatonaphthalene, 2,6-dicyanatonaphthalene, 2,7-dicyanatonaphthalene, 1,3,6-tricyanatonaphthalene, bis(4- cyanatophenyl)methane, bis(3-chloro-4-cyanatophenyl)methane, 2,2-bis(4-cyanatophenyl)propane, 2,2-bis(3,5-dichloro-4-cyanatophenyl)propane, 2,2-bis(3,5-dibromo-4- cyanatophenyl)propane, bis (4-cyanatophenyl)ether, bis (p-cyanophenoxyphenoxy)-benzene, di(4-cyanatophenyl)ketone, bis(4-cyanatophenyl)thioether, bis(4-cyanatophenyl)sulfone, tris (4-cyanatophenyl)phosphite, tris(4-cyanatophenyl)phosphate and combinations thereof.

17. The method of claim 13, wherein the photoinitiator is selected from the group consisting of aryldiazonium, triphenylsulfonium, diphenyliodonium, diaryliodosyl and triarylsulfoxonium salts.

18. The method of claim 13, wherein the composition contains about 40% to about 75% by weight dispersed silica.

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19. (TWICE AMENDED) The method of claim 13, wherein the dispersed filler includes fused silica and amorphous silica.

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20. (TWICE AMENDED) The method of claim 19, wherein a particle size of the dispersed silica is 31 microns or less.

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21. (AMENDED) The method of claim 13, wherein a coefficient of linear thermal expansion of the cured composition is from about 26 to about 39 ppm/degree C.

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22. (AMENDED) The method of claim 13, wherein a glass transition temperature of the cured composition is from about 100 to about 160 degrees C.

23. (TWICE AMENDED) The method of claim 13, wherein the composition includes from 1 to 20 parts of surface treating agents selected from the group consisting of vinyltrimethoxsilane, vinyltriethoxsilane, N(2-aminoethyl)3-aminopropylmethyldimethoxsilane, 3-aminopropylethoxsilane, 3-glycidoxypropyltrimethoxsilane, 3-glycidoxypropylmethyl dimethoxsilane and combinations thereof, based on 100 parts of the resin.

24. (AMENDED) The method of claim 13, wherein the filler is selected from the group